

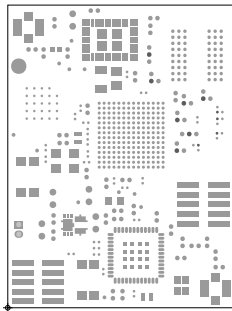
ed Module

10

Rule

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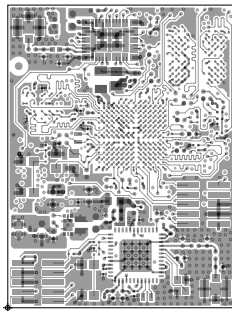
## NXP SEMICONDUCTORS

DATE: 03Dec, 2019

Rev: D

PART NO/CARD REF: iMXRT Connected Module

FILM LAYER: SMT\_SOLDER MASK TOP



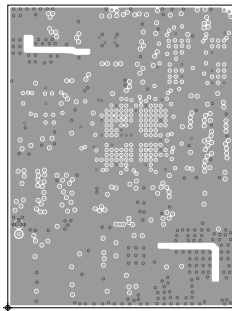
## NXP SEMICONDUCTORS

DATE: 03Dec, 2019

Rev: D

PART NO/CARD REF: iMXRT Connected Module

FILM LAYER: L1-TOP LAYER



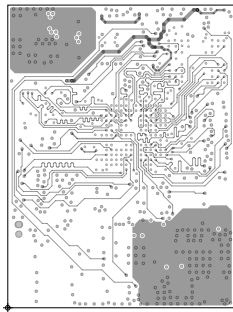
## NXP SEMICONDUCTORS

DATE: 03Dec, 2019

Rev: D

PART NO/CARD REF: iMXRT Connected Module

FILM LAYER: L2-GND PLANE



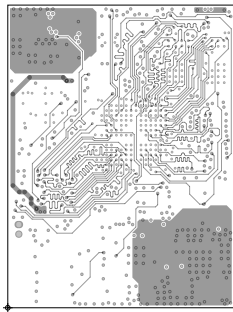
## NXP SEMICONDUCTORS

DATE: 03Dec, 2019

Rev: D

PART NO/CARD REF: iMXRT Connected Module

FILM LAYER: L3-SIGNAL



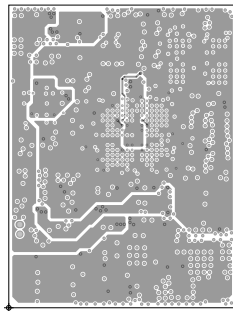
## NXP SEMICONDUCTORS

DATE: 03Dec, 2019

Rev: D

PART NO/CARD REF: iMXRT Connected Module

FILM LAYER: L4-SIGNAL



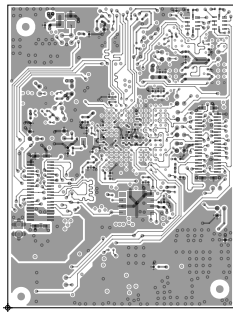
## NXP SEMICONDUCTORS

DATE: 03Dec, 2019

Rev: D

PART NO/CARD REF: iMXRT Connected Module

FILM LAYER: L5-PWR PLANE



## NXP SEMICONDUCTORS

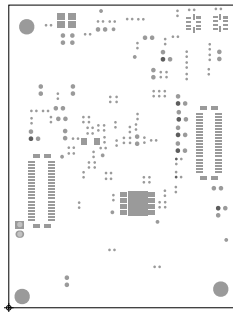
DATE: 03Dec, 2019

Rev: D

PART NO/CARD REF: iMXRT Connected Module

FILM LAYER: L6-BOTTOM LAYER





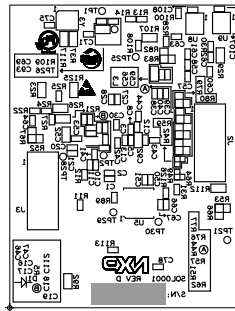
## NXP SEMICONDUCTORS

DATE: 03Dec, 2019

Rev: D

PART NO/CARD REF: iMXRT Connected Module

FILM LAYER: SMB\_SOLDER MASK BOTTOM



NXP SEMICONDUCTORS

DATE: 03Dec, 2019

Rev: D

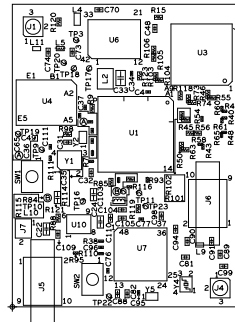
PART NO/CARD REF: iMXRT Connected Module

FILM LAYER: SLB SILKSCREEN BOTTOM

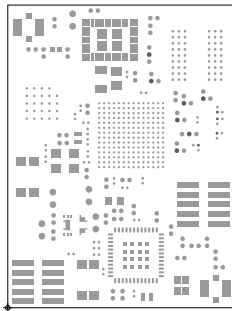


NOTE:

- 1.RECOMMENDED STENCIL THICKNESS - 4MIL
- 2.MARK APPROPRIATE DASH, REV. AND SERIAL NO. CHARACTERS TO BE PERMANENT AND LEGIBLE.
- 3.WORKMANSHIP OF ELECTRONIC ASSEMBLIES SHALL CONFORM TO IPC-A-610, CLASS 2.
- 4.ASSEMBLY IS STATIC SENSITIVE ALL PROCESS/HANDLING OPERATIONS MUST CONFORM TO E.S.D. PRACTICES CONTAINED WITHIN IPC-A-610.







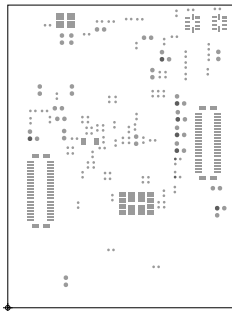
## NXP SEMICONDUCTORS

DATE: 03Dec, 2019

Rev: D

PART NO/CARD REF: iMXRT Connected Module

FILM LAYER: SPT\_SOLDER PASTE TOP



## NXP SEMICONDUCTORS

DATE: 03Dec, 2019

Rev: D

PART NO/CARD REF: iMXRT Connected Module

FILM LAYER: SPB\_SOLDER PASTE BOTTOM

